



SF325C 耐离子迁移型聚酰亚胺薄膜覆盖膜

SF325C Anti-ion Migration type PI film base coverlay

特点

- 优异的耐离子迁移性，不长枝状结晶。
- 不含卤素，阻燃性达到 UL94 VTM-0 级。
- 粘接强度高，尺寸稳定性、耐热性好。
- 溢胶量低，加工性好，适于快速压合和传统压合。
- 满足 RoHS 指令要求，不含铅、汞、镉、六价铬、多溴联苯、多溴联苯醚等。

FEATURES

- Excellent anti-ion Migration, no dendrite.
- Halogen free, Flammability UL94 VTM-0.
- High bonding strength, good dimensional stability and thermal resistance.
- Low adhesive flowing, good processability, suitable for both fast and traditional lamination style.
- Compatible with EU RoHS directive, free of Pb,Hg,Cd, Cr⁶⁺,PBB,PBDE, etc..

应用领域

挠性印制电路板用覆盖膜。

APPLICATIONS

Coverlay for FPC.

性能表 GENERAL PROPERTIES

性能项目 Test Item	测试方法 Test Method	单位 Unit	IPC 标准值* Standard	典型值 Typical Value
				SF325C 0515
溢胶量 Resin Flow	SY Method	mm	-	<0.15
剥离强度 Peel Strength (90°)	IPC-TM-650,No.2.4.9 Method A Method C	N/mm	≥0.7 ≥0.53	1.2 1.1
热应力 Thermal Stress	IPC-TM-650,No.2.4.13	-	Pass	Pass
尺寸稳定性 Dimensional Stability	SY Method	%	±0.2	MD:-0.0083 TD:-0.0021
耐化学性 Chemical Resistance	IPC-TM-650,No.2.3.2	%	≥80	>90
吸水率 Moisture Absorption	IPC-TM-650,No.2.6.2	%	≤4	1.18
体积电阻率 Volume Resistivity	IPC-TM-650,No.2.5.17	MΩ-cm	≥10 ⁶	8×10 ⁷
表面电阻 Surface Resistance	IPC-TM-650,No.2.5.17	MΩ	≥10 ⁴	8.5×10 ⁶
介电常数 10GHZ Dielectric Constant	IEC-61189-2-721	-	-	3.18
介电损耗 10GHZ Dissipation Factor	IEC-61189-2-721	-	-	0.0125

注释 Explanations: * Certified to IPC-4203/2 Epoxy adhesive on one or two sides of polyimide dielectric



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产品规格代码描述 Product Code Description

SF325C 05 15

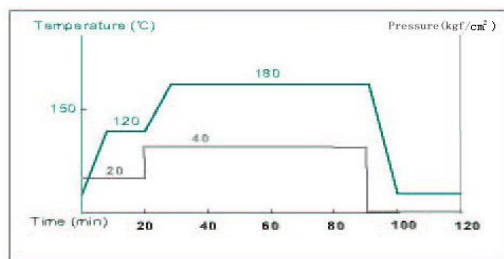
- 胶粘剂厚度 Adhesive Thickness: 15 - 15 μ m; 25 - 25 μ m
- PI膜厚度 PI film Thickness: 05 - 12.5 μ m; 10 - 25 μ m
- 生益无卤覆盖膜产品编号 Shengyi Halogen-free Coverlay Designation

常规产品表 SPECIFICATIONS OF STANDARD PRODUCTS

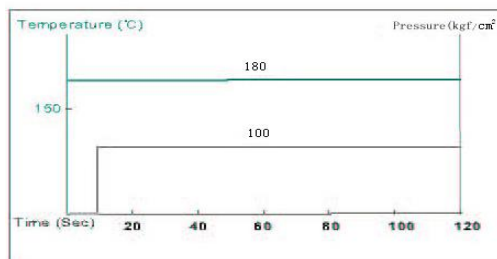
产品规格 Specifications	PI膜厚度 (μ m) PI film Thickness	胶粘剂厚度 (μ m) Adhesive Thickness	应用领域 Applications
SF325C 0515	12.5	15	挠性印制电路板用 覆盖膜 Coverlay for FPC
SF325C 0520	12.5	20	
SF325C 0525	12.5	25	
SF325C 1025	25	25	
SF325C 1030	25	30	

压板推荐 PRESS PROPOSE

HOT PRESSING CYCLE



FAST PRESSING CYCLE



传压参数根据不同设备及产品规格需作相应调整；采用快压方式，后固化条件是 160-180 $^{\circ}$ C、60-90 分钟。
The parameters of hot Pressure need to be adjusted according to different equipment and product specifications. After fast press, the curing condition is 160-180 $^{\circ}$ C for 60-90min.

包装 PURCHASING INFORMATION

产品宽度 250+2/-0mm 或 500+2/-0mm，每卷 100+2/-0 米或 200+2/-0 米；其它规格、尺寸可根据客户要求而定。SF325C is supplied in rolls and standard width of 250+2/-0mm or 500+2/-0mm. Roll length is 100+2/-0m or 200+2/-0m. Other sizes could be available upon request.

贮存条件 STORAGE CONDITION

贮存在干燥的室内；以原始包装贮存在 4-10 $^{\circ}$ C 的冷藏室里，贮存期为三个月。
Stored in the room of dryness. Three months when stored in the original packaging at 4-10 $^{\circ}$ C.